

THOMSON

DELPHION

RESEARCH

PRODUCTS

INSIDE DELPHION

Log On | Work File | Saved Searches

My Account | Products

Search: Quick/Number Boolean Advanced Derwent

The Delphion Integrated View

Get Now: ☒ PDF | More choices...Tools: Add to Work File: View: INPADOC | Jump to: ☐ Email

Title: **JP2001015912A2: MULTILAYERED PRINTED WIRING BOARD AND PRODUCTION THEREOF**

Country: **JP Japan**Kind: **A2 Document Laid open to Public inspection**Inventor: **SEKINE KOJI;**

Assignee: **IBIDEN CO LTD**
News, Profiles, Stocks and More about this company

Published / Filed: **2001-01-19 / 1999-07-02**

Application
Number: **JP1999000189208**

IPC Code: **H05K 3/46; H05K 3/00; H05K 3/28;**Priority Number: **1999-07-02 JP1999000189208**

Abstract: **PROBLEM TO BE SOLVED:** To provide a multilayered printed wiring board and a method for producing the multilayered printed wiring board by which the arrangement density of through hole can be improved and the thickness thereof be made smaller.

SOLUTION: Interlayer resin insulation layers 24 and 38 and a core substrate 50 for upper layer are built up on a core substrate 10 for lower layer. Therefore, a plurality of core substrates 10 and 50 ensure the strength of a multilayered printed wiring board, so that the core substrate can be formed thin, and the thickness of the multilayered printed wiring board be also made small. In addition, a fine non-through hole 10a can be easily made by a laser, and a through hole 14 with a small diameter can be formed.

COPYRIGHT: (C)2001,JPO

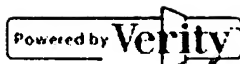
INPADOC None **Get Now:** [Family Legal Status Report](#)

Legal Status:
Family: [Show 5 known family members](#)

Other Abstract
Info: **CHEMABS 134(09)124542H CHEMABS 134(09)124542H**



Nominate



this for the Gallery...